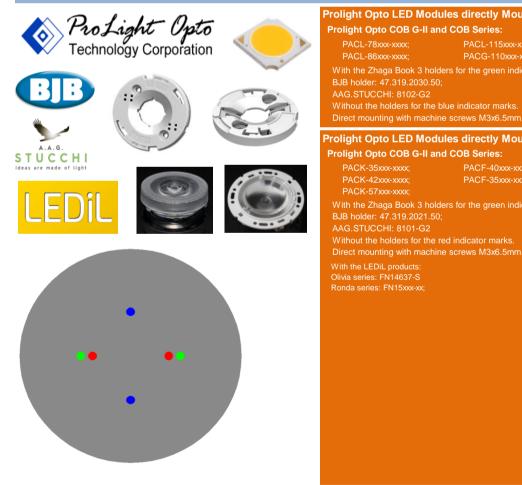


xLED-PRO-8050 Pin Fin LED Heat Sink Ø80mm for Prolight Opto

Features VS Benefits

- * The xLED-PRO-8050 Prolight Opto Pin Fin LED Heat Sinks are specifically designed for luminaires using the Prolight Opto LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,100 to 3,400 lumen.
- * Thermal resistance range Rth 2.38°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Prolight Opto COB series.
- * Diameter 80.0mm standard height 50.0mm Other heights on request.
- * Forged from highly conductive aluminum.
- Zhaga LED engine and radiator assembly is a unified future international standardization
- * Below you find an overview of Prolight Opto COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers
- can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



Tel:+86-769-39023131 Fax:+86-(020)28819702 ext:22122 Email:sales@mingfatech.com Http://www.heatsinkled.com Http://www.mingfatech.com





Prolight Opto LED Modules directly Mounting Options

With the Zhaga Book 3 holders for the green indicator marks. BJB holder: 47.319.2030.50;

Prolight Opto LED Modules directly Mounting Options

- PACF-40xxx-xxxx PACF-35xxx-xxxx
- With the Zhaga Book 3 holders for the green indicator marks. Without the holders for the red indicator marks.



xLED

xLED-PRO-8050 Pin Fin LED Heat Sink Ø80mm for Prolight Opto

Mounting Options and Drawings & Dimensions

Example:xLED-PRO-8050-B-1,2 Example:xLED-PRO-80

> Anodising Color B-Black

C-Clear

Z-Custom

Ex.order code - 12

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.

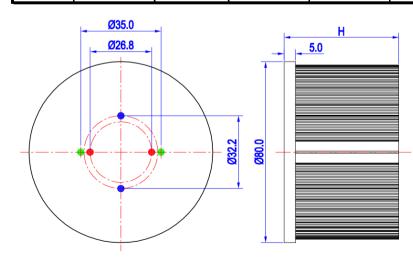
means option 1 and 2 combined

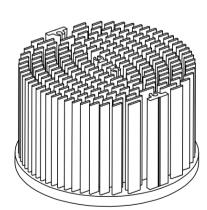
details Combinations available

Mounting Options - see graphics for

Poilspecific mechanical adaptations please contact wingral ech.
MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
OPTION			Olivia series	Ronda series	THREAD	DEPTH	DISTANCE
1	COB series (19.0*19.0)	/	FN14637-S	FN15xxx-xx;	М3	6.5mm	26.8mm/ 2-@180°
2	COB series (28.0*28.0)	/	/	1	M3	6.5mm	32.2mm/ 2-@180°
3		BJB Holder 47.319.2030.50	/	1	мз	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8102-G2					
	COB series (19.0*19.0)	BJB Holder 47.319.2021.50	FN14637-S	FN15xxx-xx;			
		AAG.STUCCHI 8101-G2					





Tel:+86-769-39023131 Fax:+86-(020)28819702 ext:22122 Email:sales@mingfatech.com Http://www.heatsinkled.com Http://www.mingfatech.com





xLED-PRO-8050 Pin Fin LED Heat Sink Ø80mm for Prolight Opto

The product deta table

xLED	Model No.	xLED-PRO-8050		
	Heatsink Size	Ф80xH50mm		
	Heatsink Material	AL1070		
	Finish	Black Anodized		
	Weight (g)	197.0		
	Dissipated power (Ths-amb,50℃)	21.0 (W)		
	Cooling surface area (mm²)	120774		
	Thermal Resistance (Rhs-amb)	2.38 (°C/W)		

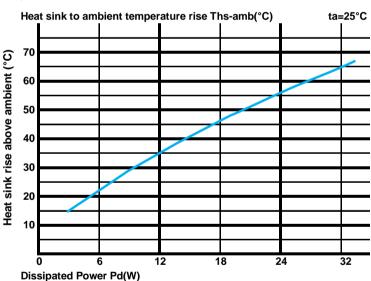
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

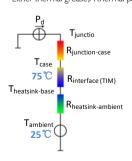
*To calculate the dissipated power please use the following formula: $Pd = Pe \times (I - \eta L)$.

Pd - Dissipated power ; Pe - Electrical power ; $\eta L =$ Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		xLED-PRO-8050		
Dissipated Power Pd(W)	6.0	3.50	21.0	
	12.0	2.92	35.0	
	18.0	2.56	46.0	
	24.0	2.29	55.0	
	32.0	2.00	64.0	



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta)/Pd$

 $\theta\,$ - Thermal Resistance [°C/W] ; $\,$ Ths - Heatsink temperature ; $\,$ Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the heat sink is $R_{\text{heatsink-ambert}}$ [°C/W], and the ambient temperature is T_{ambert} [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction}=(R_{junction-case}+R_{case-ambient})$ Pd+ $T_{ambient}$

Tel:+86-769-39023131 Fax:+86-(020)28819702 ext:22122 Email:sales@mingfatech.com Http://www.heatsinkled.com Http://www.mingfatech.com

